



CY7C199D-25SXE Status: In Production

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CY7C199D-25SXE

Automotive Qualified	Y
Min. Operating Voltage (V)	4.50
Max. Operating Voltage (V)	5.50
Min. Operating Temp. (°C)	-40
Max. Operating Temp. (°C)	125
Frequency (MHz)	N/A
Temp. Classification	Automotive(E)
Max. Operating VCCQ (V)	5.50
Min. Operating VCCQ (V)	4.50
Speed (ns)	25
Density (Kb)	256
Organization (X x Y)	32K x 8

Pricing & Inventory Availability

1-9 unit Price*	10-24 unit Price*	25-99 unit Price*	100-249 unit Price*	250-999 unit Price*	1000 + unit Price*

Availability	Quantity	Ships In	Order Now

* Prices are shown in United States dollars and are for budgetary use only for volume of 1ku

Packaging / Ordering

Package	SOIC
No. of Pins	28
Package Dimensions	705 L X 0 H X 300 W (Mils)
Package Weight	830.75 (mgs)
Package Cross Section Drawing	Download
Package Carrier	TUBE
Package Carrier Drawing / Orientation	Drawing, Package Orientation
Standard Pack Quantity	135
Minimum Order Quantity (MOQ)	135
Order Increment	135
Estimated Lead Time (days)	91
HTS Code	8542.32.0040

Quality and RoHS

Moisture Sensitivity Level (MSL)	3
Peak Reflow Temp. (°C)	260 (Cypress Reflow Profile)
RoHS Compliant	Y Print RoHS Certificate of Compliance
PB Free	Y
Lead/Ball Finish	Ni/Pd/Au
Marking	Cypress Marking Format
Package Material Declaration 28L-SOIC PB-FREE PACKAGE MATERIAL DECLARATION DATASHEET <i>Last Update: 08/13/2013</i>	
IPC 1752 Material Declaration IPC-1752-2_V1.1_SOIC 28_CML_NIPDAU_GREEN MC <i>Last Update: 07/04/2012</i> SOIC 28 - 001-80414 <i>Last Update: 08/29/2012</i>	
RoHS Analysis Certificates (CoA) PACKAGE ROHS ANALYSIS REPORT - SOIC (SZ20,24,28,32) SOJ (VZ28,32,36,44) SNC (SY28) SSOP (SP48) USING MOLD COMPOUND KEG6000DA, ADHESIVE QMI509, NIPDAU - CML ASSEMBLY <i>Last Update: 07/03/2012</i> TSOP 28 - 001-79768 <i>Last Update: 06/28/2012</i>	
Device Qualification Reports  FIT/MTBF, ESD (HBM/CDM) and Latch-up data available in the Device Qualification Report. QTP_113201_001-83867.pdf <i>Last Update: 07/05/2013</i>	

Technical Documents

Application Notes (1)
[AN6081 - Interfacing 90-nm Cypress Asynchronous SRAMs in Legacy Systems](#) *Last Update: 19/12/2012*

Support and Community

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